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Semiconductor devices - Mechanical and climatic test methods - Part 26: Electrostatic discharge (ESD) sensitivity testing - Human body model (HBM)

EESTI STANDARDI EESSÖNA

NATIONAL FOREWORD

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EUROPEAN STANDARD
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English Version

Semiconductor devices - Mechanical and climatic test methods -
Part 26: Electrostatic discharge (ESD) sensitivity testing -
Human body model (HBM)
(IEC 60749-26:2013)

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 26: Essai de sensibilité
aux décharges électrostatiques (DES) - Modèle du corps
humain (HBM)
(CEI 60749-26:2013)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 26: Prüfung der Empfindlichkeit gegen
elektrostatische Entladungen (ESD) - Human Body Model
(HBM)
(IEC 60749-26:2013)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

This document (EN 60749-26:2014) consists of the text of IEC 60749-26:2013 prepared by IEC/TC 47 "Semiconductor devices", in collaboration with Technical Committee 101.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2015-04-14
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2017-04-14

This document supersedes EN 60749-26:2006.

EN 60749-26:2014 includes the following significant technical changes with respect to EN 60749-26:2006:

- a) descriptions of oscilloscope and current transducers have been refined and updated;
- b) the HBM circuit schematic and description have been improved;
- c) the description of stress test equipment qualification and verification has been completely re-written;
- d) qualification and verification of test fixture boards has been revised;
- e) a new section on the determination of ringing in the current waveform has been added;
- f) some alternate pin combinations have been included;
- g) allowance for non-supply pins to stress to a limited number of supply pin groups (associated non-supply pins) and allowance for non-supply to non-supply (i.e., I/O to I/O) stress to be limited to a finite number of 2 pin pairs (coupled non-supply pin pairs);
- h) explicit allowance for HBM stress using 2 pin HBM testers for die only shorted supply groups.

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Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here:
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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-27	-	Semiconductor devices - Mechanical and climatic test methods - Part 27: Electrostatic discharge (ESD) sensitivity testing - Machine model (MM)	EN 60749-27	-

CONTENTS

FOREWORD	4
1 Scope	6
2 Normative references	6
3 Terms and definitions	6
4 Apparatus and required equipment	9
4.1 Waveform verification equipment	9
4.2 Oscilloscope	10
4.3 Additional requirements for digital oscilloscopes	10
4.4 Current transducer (inductive current probe)	10
4.5 Evaluation loads	10
4.6 Human body model simulator	10
4.7 HBM test equipment parasitic properties	11
5 Stress test equipment qualification and routine verification	11
5.1 Overview of required HBM tester evaluations	11
5.2 Measurement procedures	11
5.2.1 Reference pin pair determination	11
5.2.2 Waveform capture with current probe	12
5.2.3 Determination of waveform parameters	12
5.2.4 High voltage discharge path test	15
5.3 HBM tester qualification	15
5.3.1 HBM ESD tester qualification requirements	15
5.3.2 HBM tester qualification procedure	15
5.4 Test fixture board qualification for socketed testers	16
5.5 Routine waveform check requirements	17
5.5.1 Standard routine waveform check description	17
5.5.2 Waveform check frequency	17
5.5.3 Alternate routine waveform capture procedure	18
5.6 High voltage discharge path check	18
5.6.1 Relay testers	18
5.6.2 Non-relay testers	18
5.7 Tester waveform records	18
5.7.1 Tester and test fixture board qualification records	18
5.7.2 Periodic waveform check records	18
5.8 Safety	19
5.8.1 Initial set-up	19
5.8.2 Training	19
5.8.3 Personnel safety	19
6 Classification procedure	19
6.1 Devices for classification	19
6.2 Parametric and functional testing	19
6.3 Device stressing	19
6.4 Pin categorization	20
6.4.1 General	20
6.4.2 No connect pins	20
6.4.3 Supply pins	20
6.4.4 Non-supply pins	21

6.5	Pin groupings	21
6.5.1	Supply pin groups.....	21
6.5.2	Shorted non-supply pin groups	22
6.6	Pin stress combinations.....	22
6.6.1	Pin stress combination categorisation.....	22
6.6.2	Non-supply and supply to supply combinations (1, 2, ... N).....	24
6.6.3	Non-supply to non-supply combinations.....	25
6.7	Testing after stressing	26
7	Failure criteria	26
8	Component classification.....	26
Annex A (informative)	HBM test method flow chart.....	27
Annex B (informative)	HBM test equipment parasitic properties	30
Annex C (informative)	Example of testing a product using Table 2, Table 3, or Table 2 with a two-pin HBM tester	34
Annex D (informative)	Examples of coupled non-supply pin pairs.....	40
Figure 1 – Simplified HBM simulator circuit with loads	11	
Figure 2 – Current waveform through shorting wires	13	
Figure 3 – Current waveform through a 500 Ω resistor.....	14	
Figure 4 – Peak current short circuit ringing waveform.....	15	
Figure B.1 – Diagram of trailing pulse measurement setup.....	30	
Figure B.2 – Positive stress at 4 000 V	31	
Figure B.3 – Negative stress at 4 000 V	31	
Figure B.4 – Illustration of measuring voltage before HBM pulse with a Zener diode or a device	32	
Figure B.5 – Example of voltage rise before the HBM current pulse across a 9,4 V Zener diode	32	
Figure C.1 – Example to demonstrate the idea of the partitioned test.....	35	
Table 1 – Waveform specification	17	
Table 2 – Preferred pin combinations sets	23	
Table 3 – Alternative pin combinations sets	24	
Table 4 – HBM ESD component classification levels.....	26	
Table C.1 – Product testing in accordance with Table 2	36	
Table C.2 – Product testing in accordance with Table 3	37	
Table C.3 – Alternative product testing in accordance with Table 2	38	